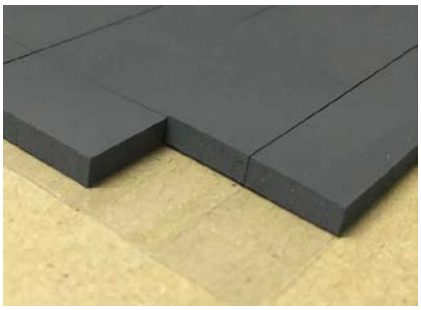
TP300-H55-AM1

Thermally Conductive Electromagnetic Wave Absorbing Pad

The TP300-H55-AM1 is a silicone-based pad engineered with wave-absorbing ceramic filler. It provides combined thermal management and EMI shielding by dissipating heat and absorbing electromagnetic radiation, making it an ideal solution for electronic communication devices.



Features and Benefits

- Thermal Conductivity : 3.0 W/(m·K)
- Excellent electromagnetic shielding function
- Excellent high and low temperature and mechanical properties
- High chemical stability

Typical Applications

- Electronic communication equipment
- Digital products, computers
- Medical electronic
- Automotive electronics
- High frequency module

Typical Properties		
Properties	**Attribute**	**Test Method**
Color	Grey	Visual
Thickness(mm)	1.0 to 10.0	ASTM D374
Density(g/cc)	3.8	ASTM D792
Reflectivity (dB)	＜-5 (2~6GHz)	GJB:2038A-2011
Hardness(Shore 00)	55	ASTM D2240
Weight Damnify(%)	≤1.0	Filter paper adsorption @25% compression/125°C/48h
Usage Temperature(°C)	- 40 to 150	/
Flammability	V-0	UL 94
Shelf Life(Month)	12	Temperature <40°C avoid extrusion and exposure to the sun
Electrical		
Volume Resistivity(Ω·cm)	＞10^{12}	ASTM D257
Dielectric Constant	≤12.0	ASTM D150 @10MHz
Thermal		
Thermal conductivity(W/(m·K))	3.0	ASTM D5470

PS: 1. The above shelf life is mainly recommended for customers to use within 12 months. Exceeding the shelf life may cause changes in product release force, affecting assembly and use. The material itself will not deteriorate. If it exceeds the shelf life, as long as the release force and assembly of the product are verified to be correct, it can be extended indefinitely.

2. The breakdown voltage is measured according to the ASTM D149 test method using manual boosting, but the voltage cannot rise, so the breakdown voltage test value is 0.

AOK 傲川科技 AOCHUAN TECHNOLOGY